

# WSK063

## 半导体晶圆切片机

WSK063 SiC slicing machine (slurry cutting)



### 技术规格参数 Specifications and Technical Parameters

<b>工件 workpiece</b>	
横断面 cross section	≤Φ330mm
长度 length	2×300mm; 1×600mm
厚度 thickness	0.20200mm (必须调整制程 must adjust manufacturing process)
<b>切割速率 cutting rate</b>	
线速度 linear velocity	最大MAX.30m/min 速率 rate 可以设定 can set*
快速移动 fast move	200mm/min
工作行程 working stroke	最大MAX.385mm
<b>钢线 wire</b>	
芯线径 diameter of core wire (external diameter)	0.055-0.400mm
钢线长度 length of wire	按伟纶而定 according to wire wheel
钢线方向 direction of wire	前进或后退切割 forward or backward/double directional cutting
预先张力 pre-tension	最大50N (端绳钢线直径而定) max. 50N (according to diameter of wire)
<b>导轮 guide wheel</b>	
直径 diameter	Φ192mm
长度 length	600mm...
个数 number	3
主电机功率 main motor power	最大 max. 3x30KW
轴距 (左右) wheelbase (left & right)	540mm
轴距 (上下) wheelbase (up & down)	250mm
<b>钢线偏向滚轮 offset roller</b>	
直径 diameter	160mm
个数 number	2x3(0)
<b>卷绕线盘 winding coil</b>	
卷绕轴工作高度 working height of winding shaft	1355mm
卷绕线盘 winding coil	WSK0275521-367
钢线盘有磁吸 winding coil of magnet	JA1100
<b>切削液供应 cutting compound supply</b>	
切削液箱容量 capacity of cutting tank	300L...
切削液温度切削液温度 constant temperature of cutting fluid	可选择设备 0.1~20.0℃ 可设 settable 0.1~20.0℃
泵浦输送量 pump rate	最大MAX.12000L/h 可设 settable 使用伟纶注油器 adjustable measure with flow meter and display
冷却水流入温度 inflow temperature of cooling water	15℃±1℃
<b>控制系統 controling system</b>	
安全 type	SP 安全制器 safety device
CNC 控制機 Cnc controller	SP 控制機 SP controller
PS 控制機 P.S. controller	SP 控制機 SP controller
供貨商 supplier	西门子 (Siemens)
<b>外观尺寸及总重量 outline dimension and total weight</b>	
长度 length	4470mm
宽度 width	2100mm
高度 height	3500mm
总重量 total weight	约13000kg

### 设备用途和特性

- 本机床适用于半导体行业用于半导体晶圆的切片，是半导体行业硅片加工的主要配套设备。硅锭横断面最大为Φ330mm，切片厚度最小为0.2mm，必须调整制程，一次装夹最大可切片达1300(2200)片，是半导体行业硅片生产厂家的优选设备。
- 本机床特点：
- 1、两个钢线导轮驱动，收（放）线驱动，及收（放）线的排线驱动，均采用伺服驱动，同步协调。
- 2、钢线涨紧力的检测控制也通过伺服电机驱动（恒张力、恒速度）。
- 3、工件进给由伺服电机通过滚珠丝杆拖动，进给量的大小与钢线的引导速度相匹配。
- 4、切削液的搅拌与输送。切削液管道通过热交换器达到恒温及计量器计量，与切片速度相适应。
- 5、本机床为高新技术集中的产品。

### Applications and structural features

- the machine is used for cutting semiconductor wafer, which is main matched processing equipment. The max dimension of cross section Φ330mm, the minimum thickness of section 0.2mm, adjust processing procedure, it may cut 1300(2200) slices at one clamp. The optimized equipment for semiconductor manufacturers.
- features
- two wire guide wheel drive, winding up and down drive, and wire guide wheel drive, these apply servo drive, and must be synchronized.
- detection control of wire tension of wire by servo motor (constant tension)
- workpiece feed is driven by servo motor, and feed rate is matched with guiding speed of wire.
- agitation and conveying of cutting fluid, cutting fluid pipe can reach up constant temperature through heat exchanger, matching the slicing rate.
- this machine is an integrated high-tech product.